

International Application No.: PCT/JP2005/021544

U.S. Patent Application No.: Unknown

May 30, 2006

Page 3 of 11

**IN THE ABSTRACT:**

Please replace the Abstract of the Disclosure originally filed with the above-identified patent application with the following new Abstract of the Disclosure:

#### ABSTRACT OF THE DISCLOSURE

A laminated ceramic electronic component includes a plurality of ceramic green sheets. In each of the ceramic green sheets, which are not backed with a carrier film, coil conductor patterns and lead-out electrodes are formed by a screen printing method and simultaneously a conductive paste is filled in holes for via holes to form via holes. The coil conductor patterns include first lands provided at one end of the coil conductor patterns so as to cover the via holes for connection between layers and second lands to be connected to the via holes provided at the other end of the conductive patterns. The second lands are larger in diameter than the first lands, such that the area of the second lands is about 1.10 to about 2.25 times as wide as the area of the first lands.